

INTEGRATED CIRCUIT AND METHOD
OF PRODUCING A CARRIER WAFER FOR AN INTEGRATED CIRCUIT

ABSTRACT

A method of producing a carrier wafer for an integrated circuit is disclosed. The method comprises the steps of providing a carrier wafer having a plurality of bump pads and a plurality of wire bond pads; providing a passivation layer on the carrier wafer; etching a passivation layer over at least a portion of the plurality of bump pads; applying solder bumps on the plurality of bump pads; and separately etching the passivation layer over at least a portion of the plurality of wire bond pads. An integrated circuit employing a flip chip is also disclosed.